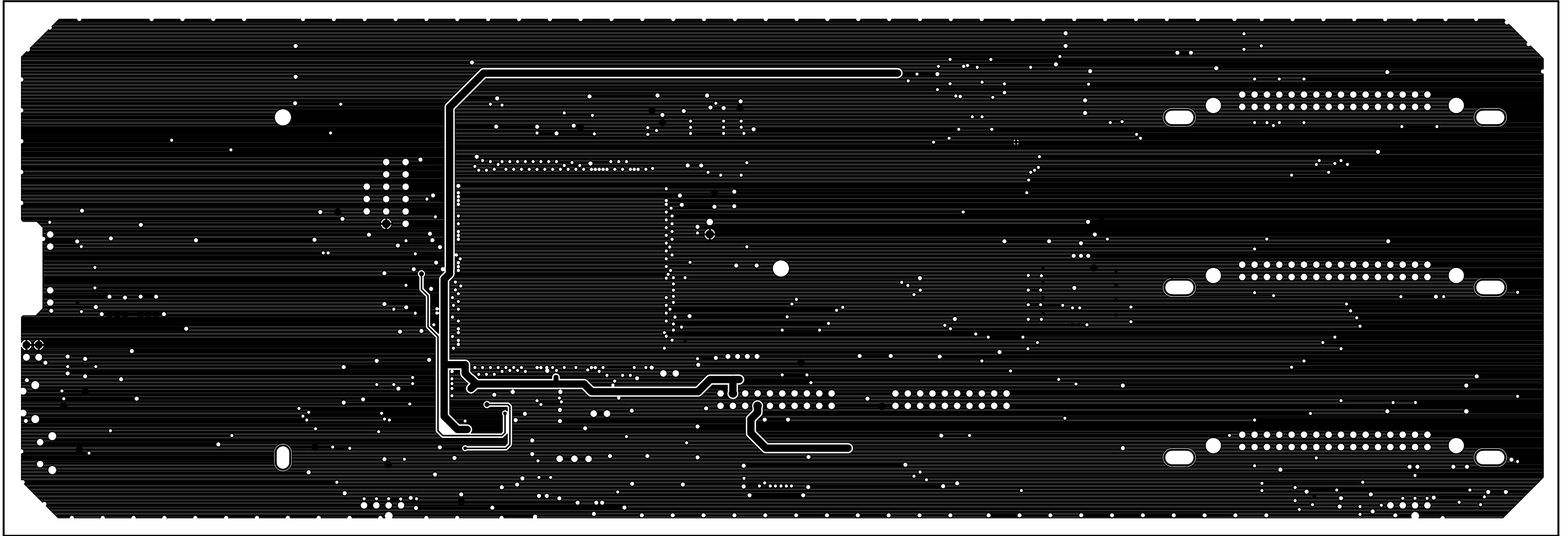


LAYER 2

FABRICATE PER IPC-6012D CLASS II  
MATERIAL PER IPC-4101/126, 4 LAYER, SMOBC (COLOR RED)  
BOARD THICKNESS .062" +/- .007", 1 oz. Cu OUTER LAYERS,  
1 oz. Cu INNER LAYERS  
DIELECTRIC THICKNESS OUTER CORES = .008"(0.2mm)  
DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
TRACE IMPEDANCE- NOT APPLICABLE  
FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI  
TECHEN INC 508-478-0042  
PCB: 742905 RA 06-18-2018  
Assm: 742904 Revision - Reference applicable BOM



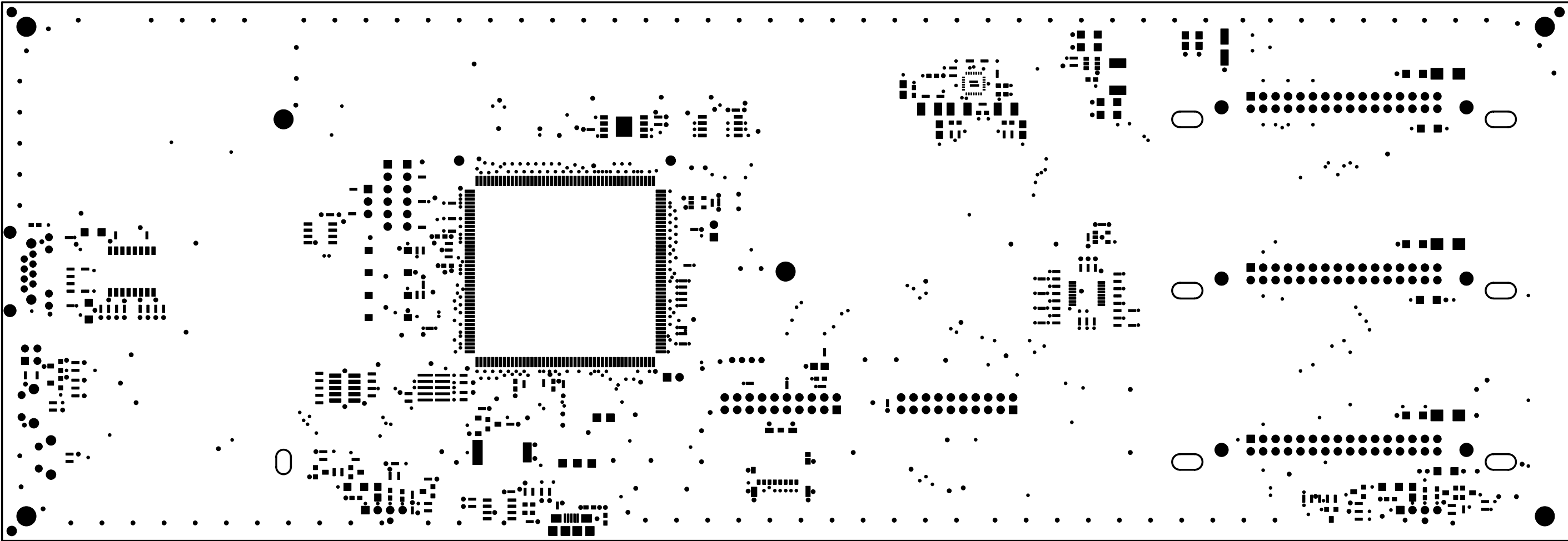
LAYER 3

FABRICATE PER IPC-6012D CLASS II  
MATERIAL PER IPC-4101/126, 4 LAYER, SMOBC (COLOR RED)  
BOARD THICKNESS .062" +/- .007", 1 oz. Cu OUTER LAYERS,  
1 oz. Cu INNER LAYERS  
DIELECTRIC THICKNESS OUTER CORES = .008"(0.2mm)  
DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
TRACE IMPEDANCE- NOT APPLICABLE  
FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI  
  
TECHEN INC 508-478-0042  
PCB: 742905 RA 06-18-2018  
Assm: 742904 Revision - Reference applicable BOM





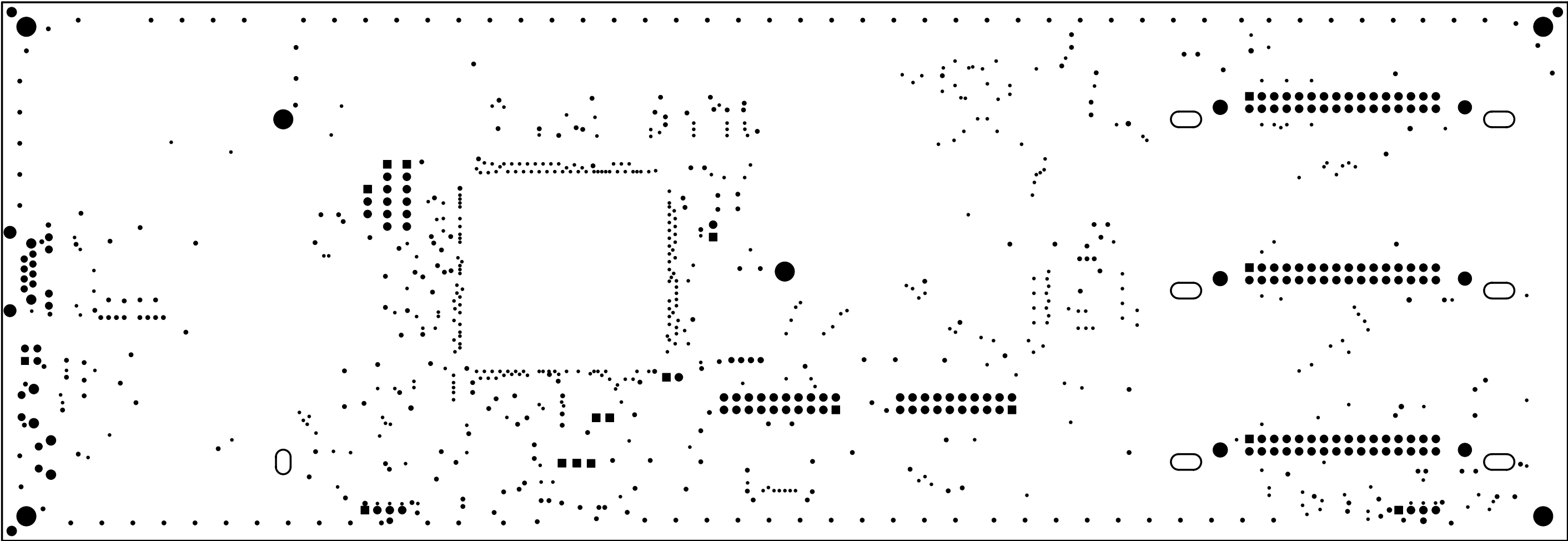




SOLDER MASK TOP

FABRICATE PER IPC-6012D CLASS II  
MATERIAL PER IPC-4101/126, 4 LAYER, SMOBC (COLOR RED)  
BOARD THICKNESS .062" +/- .007", 1 oz. Cu OUTER LAYERS,  
1 oz. Cu INNER LAYERS  
DIELECTRIC THICKNESS OUTER CORES = .008"(0.2mm)  
DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
TRACE IMPEDANCE- NOT APPLICABLE  
FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI

TECHEN INC 508-478-0042  
PCB: 742905 RA 06-18-2018  
Assm: 742904 Revision - Reference applicable BOM

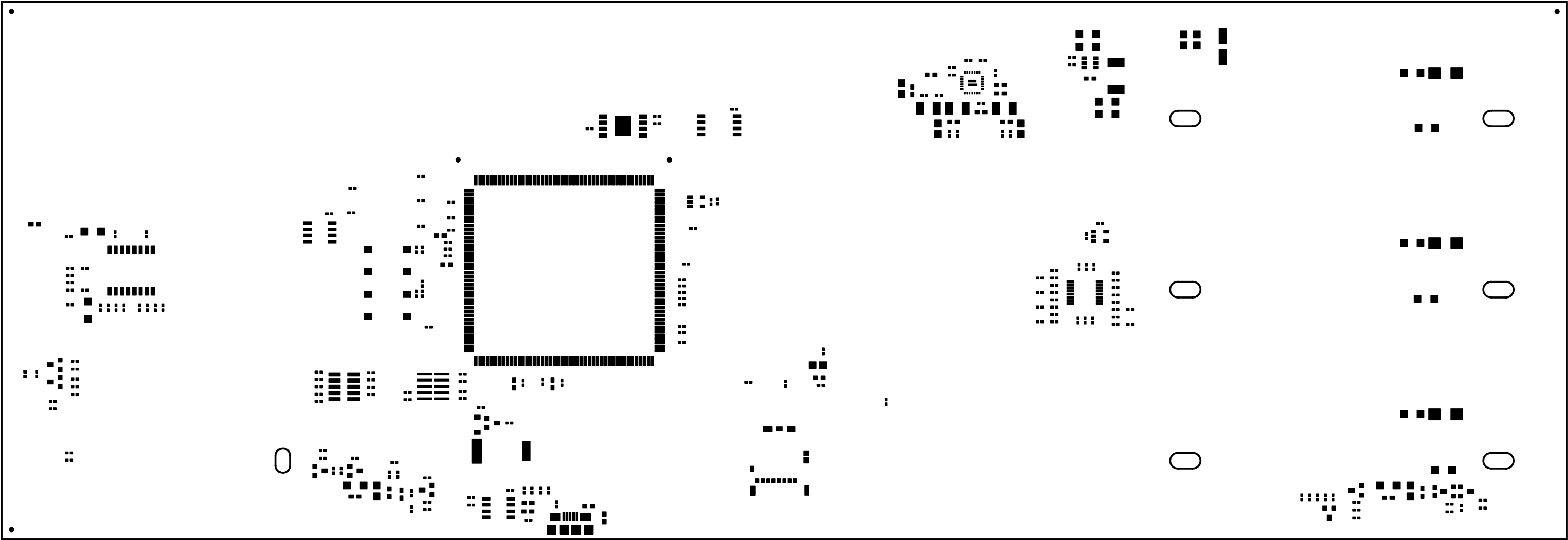


SOLDER MASK BOTTOM

FABRICATE PER IPC-6012D CLASS II  
MATERIAL PER IPC-4101/126, 4 LAYER, SMOBC (COLOR RED)  
BOARD THICKNESS .062" +/- .007", 1 oz. Cu OUTER LAYERS,  
1 oz. Cu INNER LAYERS  
DIELECTRIC THICKNESS OUTER CORES = .008"(0.2mm)  
DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
TRACE IMPEDANCE- NOT APPLICABLE  
FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI

TECHEN INC 508-478-0042  
PCB: 742905 RA 06-18-2018  
Assm: 742904 Revision - Reference applicable BOM

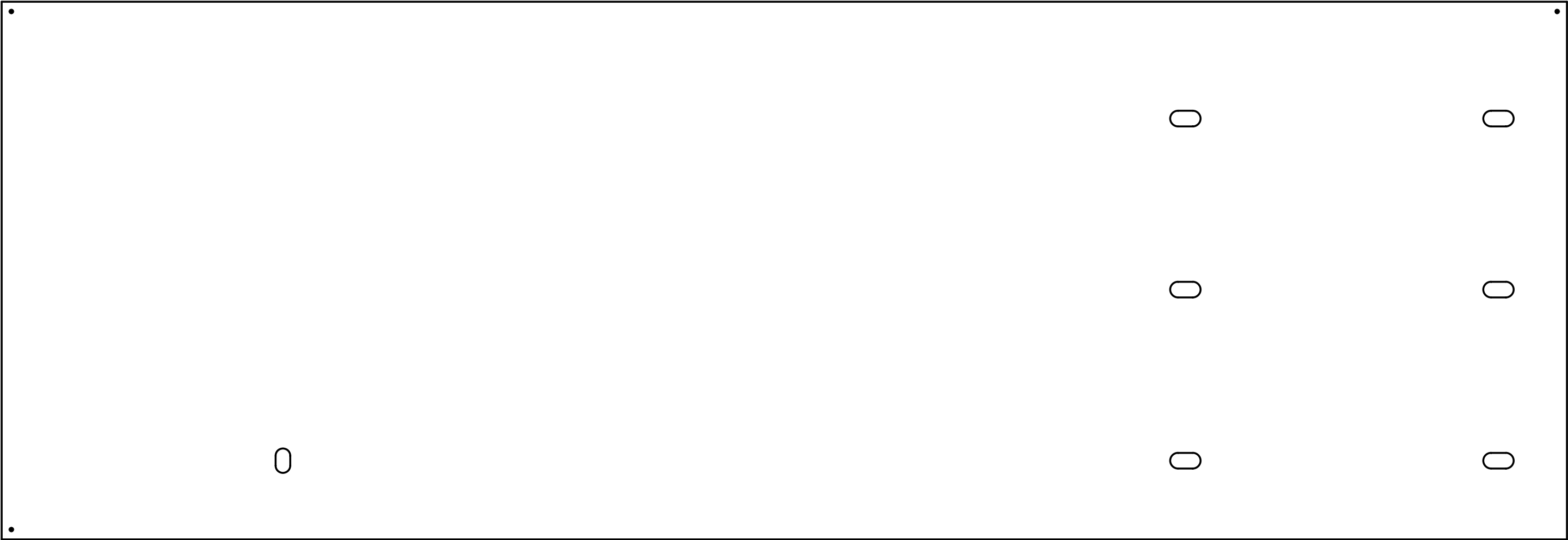




PASTE MASK TOP

FABRICATE PER IPC-6012D CLASS II  
MATERIAL PER IPC-4101/126, 4 LAYER, SMOBC (COLOR RED)  
BOARD THICKNESS .062" +/- .007", 1 oz. Cu OUTER LAYERS,  
1 oz. Cu INNER LAYERS  
DIELECTRIC THICKNESS OUTER CORES = .008"(0.2mm)  
DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
TRACE IMPEDANCE- NOT APPLICABLE  
FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI

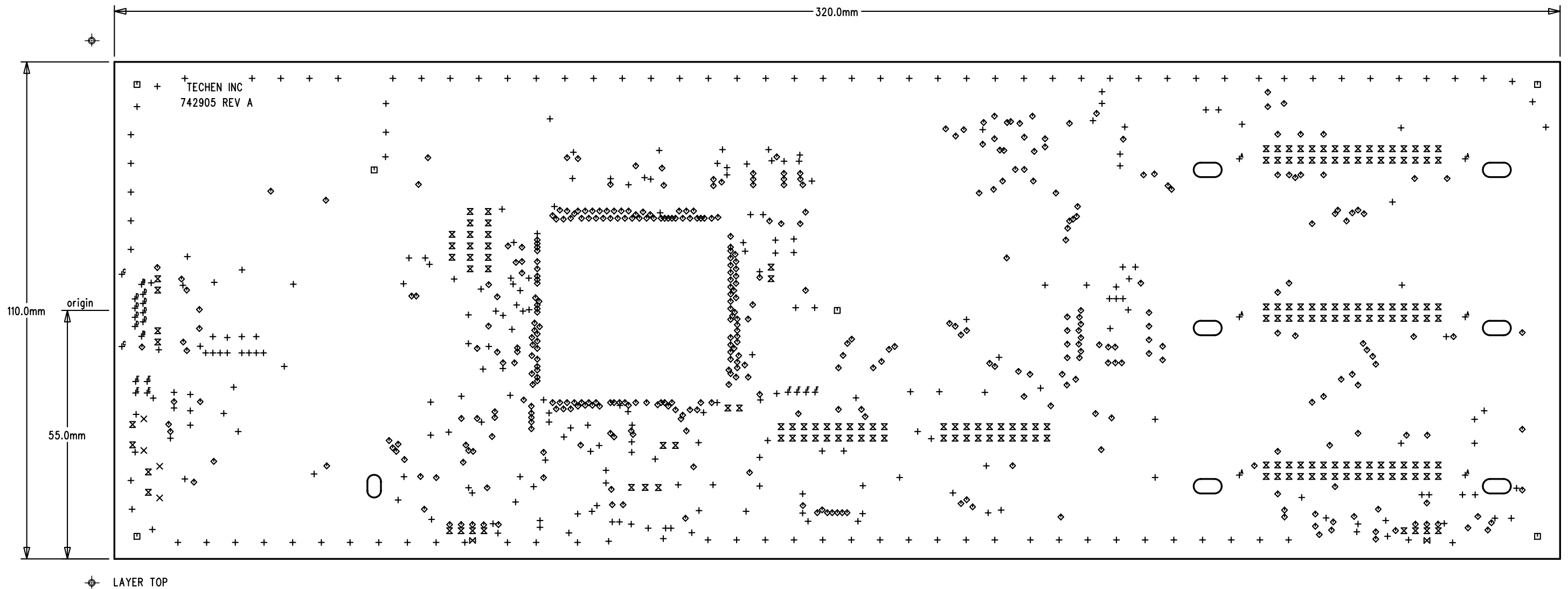
TECHEN INC 508-478-0042  
PCB: 742905 RA 06-18-2018  
Assm: 742904 Revision - Reference applicable BOM



PASTE MASK BOTTOM

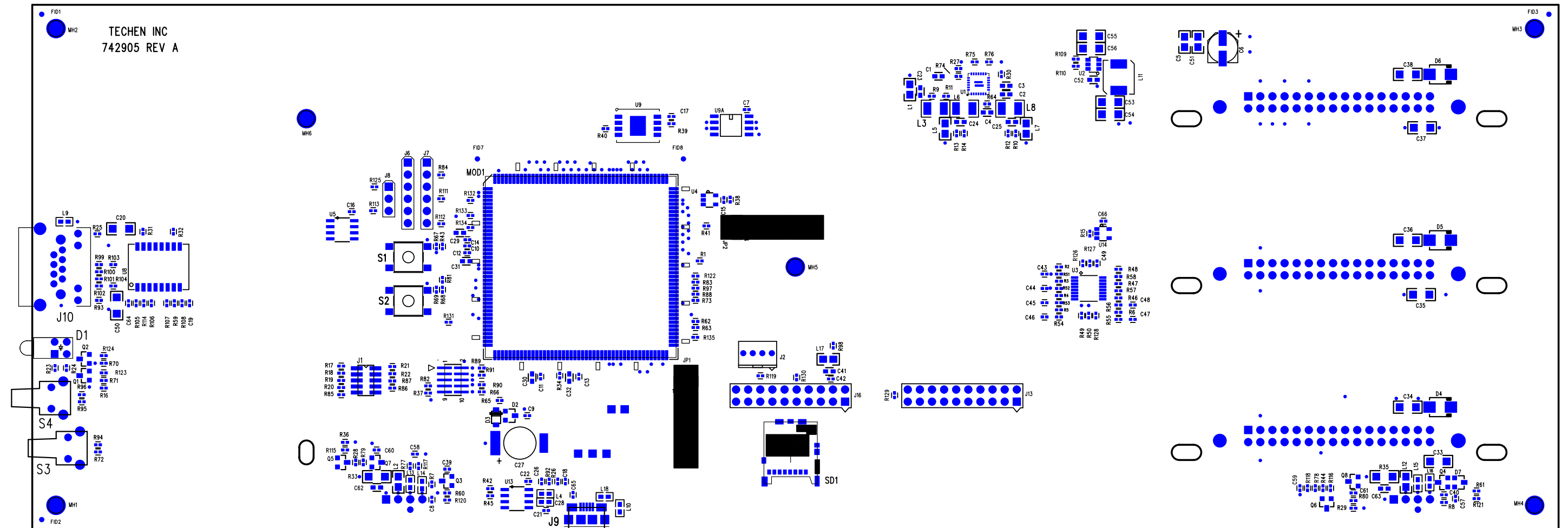
FABRICATE PER IPC-6012D CLASS II  
MATERIAL PER IPC-4101/126, 4 LAYER, SMOBC (COLOR RED)  
BOARD THICKNESS .062" +/- .007", 1 oz. Cu OUTER LAYERS,  
1 oz. Cu INNER LAYERS  
DIELECTRIC THICKNESS OUTER CORES = .008"(0.2mm)  
DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
TRACE IMPEDANCE- NOT APPLICABLE  
FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI

TECHEN INC 508-478-0042  
PCB: 742905 RA 06-18-2018  
Assm: 742904 Revision - Reference applicable BOM



FABRICATE PER IPC-6012D CLASS II  
MATERIAL PER IPC-4101/126, 4 LAYER, SMOBC (COLOR RED)  
BOARD THICKNESS .062" +/- .007", 1 oz. Cu OUTER LAYERS,  
1 oz. Cu INNER LAYERS  
DIELECTRIC THICKNESS OUTER CORES = .008"(0.2mm)  
DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
TRACE IMPEDANCE- NOT APPLICABLE  
FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI  
TECHEN INC 508-478-0042  
PCB: 742905 RA 06-18-2018  
Assm: 742904 Revision - Reference applicable BOM

DRILL CHART UNITS (MILS)				
SIZE	QTY	SYM	PLATED	TOL
20	316	+	YES	+/-3 mils
52	4	×	YES	+/-3 mils
118.11	6	□	YES	+/-3 mils
12	423	◇	YES	+/-3 mils
40	176	⊗	YES	+/-3 mils
49	2	⊠	YES	+/-3 mils
110.24	6	+ <sup>A</sup>	YES	+/-3 mils
70.87	2	+ <sup>B</sup>	YES	+/-3 mils
78.74	2	+ <sup>C</sup>	YES	+/-3 mils
35	8	+ <sup>D</sup>	YES	+/-3 mils
43	4	+ <sup>E</sup>	YES	+/-3 mils
27.53	4	+ <sup>F</sup>	YES	+/-3 mils



LAYER TOP  
SILKSCREEN ASSY

FABRICATE PER IPC-6012D CLASS II  
MATERIAL PER IPC-4101/126, 4 LAYER, SMOBC (COLOR RED)  
BOARD THICKNESS .062" +/- .007", 1 oz. Cu OUTER LAYERS,  
1 oz. Cu INNER LAYERS  
DIELECTRIC THICKNESS OUTER CORES = .008"(0.2mm)  
DIELECTRIC THICKNESS CENTER CORE, ADJUST FOR FABRICATION  
TRACE IMPEDANCE- NOT APPLICABLE  
FINISH- IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE LPI

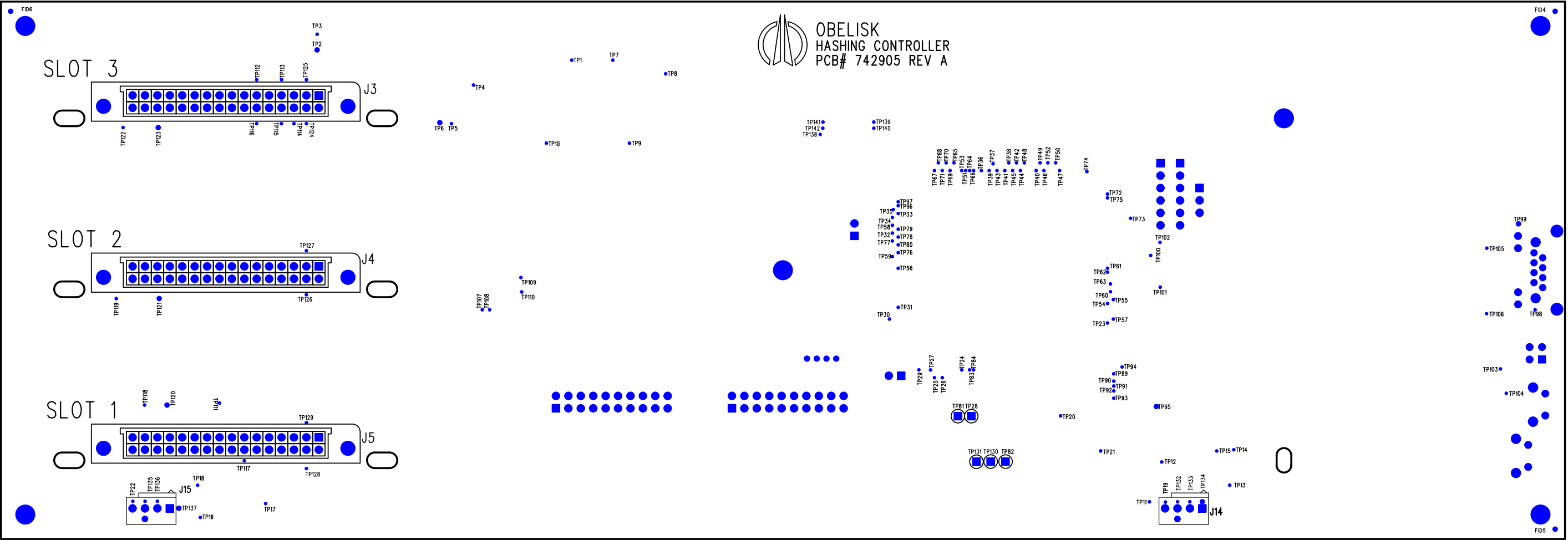
TECHEN INC 508-478-0042  
PCB: 742905 RA 06-18-2018  
Assm: 742904 Revision - Reference applicable BOM



Asm: 742904 Revision - Reference applicable BOM  
PCB: 742905 RA 06-18-2018  
TECHN INC 208-478-0045

FINISH-IMMERSION GOLD AFTER SOLDERMASK, SILKSCREEN WHITE INI  
TRACE IMPEDANCE- NOT APPLICABLE  
DIELECTRIC THICKNESS CENTER CORE ADJUST FOR FABRICATION  
DIELECTRIC THICKNESS OUTER CORES = .008"(.2mm)  
1 oz. Cu INNER LAYERS  
BOARD THICKNESS .063" +\-.003", 1 oz. Cu OUTER LAYERS  
MATERIAL PER IPC-4101\126, 4 LAYER, SMOBC (COLOR RED)  
FABRICATE PER IPC-6013D CLASS II

SILKSCREEN BOTTOM



OBELISK  
HASHING CONTROLLER  
PCB# 742905 REV A